



# LDA100 Optocoupler, Bidirectional Input Single-Transistor Output

Parameter	Rating	Units
Breakdown Voltage BV <sub>CEO</sub>	30	V <sub>P</sub>
Current Transfer Ratio (Typical)	300	%
Saturation Voltage	0.5	V
Input Control Current	1	mA

#### **Features**

- 3750V<sub>rms</sub> Input/Output Isolation
- Low Drive Power Requirements (TTL/CMOS Compatible)
- · No Moving Parts
- High Reliability
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- · Small 6-Pin Package, Thru-Hole or Surface Mount
- · Machine Insertable, Wave Solderable
- Surface Mount Tape & Reel Version Available

## **Applications**

- Telecom Switching
- · Tip/Ring Circuits
- · Modem Switching (Laptop, Notebook, Pocket Size)
- Loop Detect
- Ringing Detect
- Current Sensing

#### **Description**

The LDA100 is a bidirectional-input optocoupler with a single-transistor output. Optically coupled technology provides a  $3750V_{rms}$  isolation barrier between the input and the output.

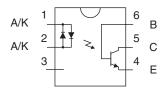
## **Approvals**

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950-1 Certified Component: TUV Certificate B 09 07 49410 006

## **Ordering Information**

Part Number	Description
LDA100	6-Pin DIP (50/Tube)
LDA100S	6-Pin Surface Mount (50/Tube)
LDA100STR	6-Pin Surface Mount (1000/Reel)

## **Pin Configuration**











# Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units	
Breakdown Voltage	30	$V_P$	
Input Control Current	50	mA	
Peak (10ms)	1	Α	
Power Dissipation			
Input <sup>1</sup>	150	mW	
Phototransistors <sup>2</sup>	150	ITIVV	
Isolation Voltage, Input to Output	3750	V <sub>rms</sub>	
Operational Temperature	-40 to +85	°C	
Storage Temperature	-40 to +125	°C	

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

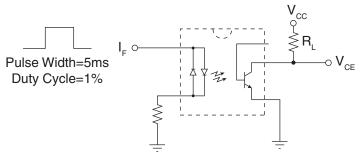
# **Electrical Characteristics @ 25°C (Unless Otherwise Noted)**

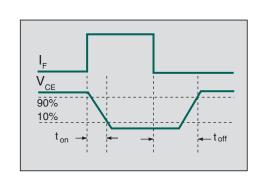
Parameters	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics	·					
Phototransistor Breakdown Voltage	I <sub>C</sub> =10μA	BV <sub>CEO</sub>	30	85	-	V
Phototransistor Dark Current	V <sub>CE</sub> =5V, I <sub>F</sub> =0mA	I <sub>CEO</sub>	-	-	500	nA
Saturation Voltage $I_C=2\text{mA}, I_F=1$		V <sub>CE(sat)</sub>	-	-	0.5	V
Current Transfer Ratio	I <sub>F</sub> =1mA, V <sub>CE</sub> =0.5V	CTR	33	300	-	%
Output Capacitance	25V, f=1MHz	C <sub>OUT</sub>	-	6	-	pF
Input Characteristics				•	•	
Input Control Current	I <sub>C</sub> =0.33mA, V <sub>CE</sub> =0.5V	I <sub>F</sub>	-	-	1	mA
Input Voltage Drop	I <sub>F</sub> =5mA	V <sub>F</sub>	0.9	1.2	1.4	V
Common Characteristics	•			•		
Input to Output Capacitance	-	C <sub>I/O</sub>	-	3	-	pF

# Switching Characteristics @ 25°C

Characteristic	Symbol	Test Condition	Тур	Units
Turn-On Time	t <sub>on</sub>	$V_{CC}$ =5V, $I_F$ =2mA, $R_L$ =1K $\Omega$	7	
Turn-Off Time	t <sub>off</sub>		20	μ\$

#### Switching Time Test Circuit



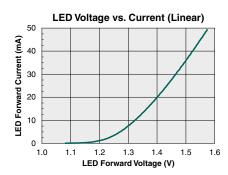


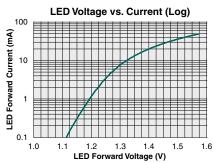
<sup>&</sup>lt;sup>1</sup> Derate linearly 1.33mW / °C

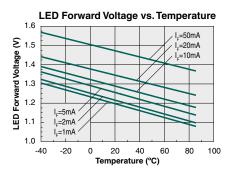
<sup>&</sup>lt;sup>2</sup> Derate linearly 2mW / °C

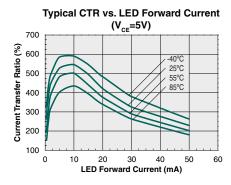


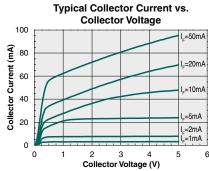
## PERFORMANCE DATA @25°C (Unless Otherwise Noted)\*

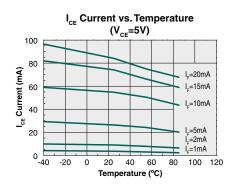


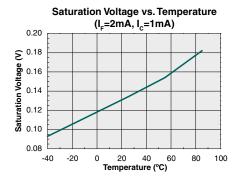


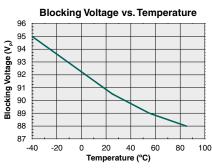


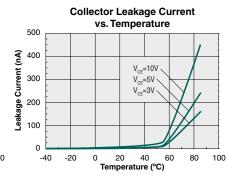


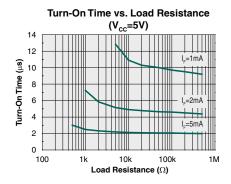


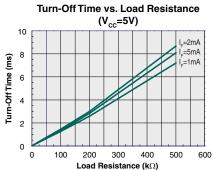












<sup>\*</sup>The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.



#### **Manufacturing Information**

#### **Moisture Sensitivity**

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
LDA100 / LDA100S	MSL 1

#### **ESD Sensitivity**



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

#### **Reflow Profile**

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
LDA100 / LDA100S	250°C for 30 seconds

#### **Board Wash**

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.



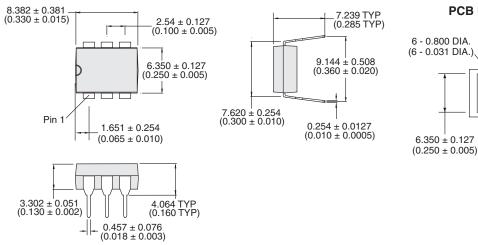




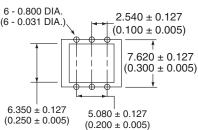


#### **Mechanical Dimensions**

#### **LDA100**

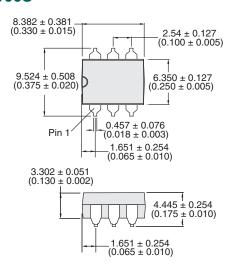


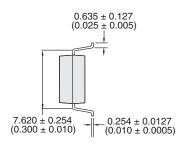
#### **PCB Hole Pattern**



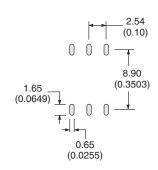
Dimensions mm (inches)

#### **LDA100S**





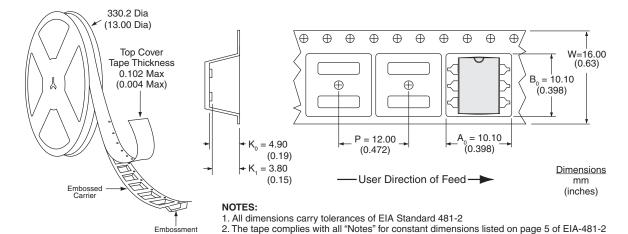
#### **PCB Land Pattern**



Dimensions mm (inches)



## LDA100STR Tape & Reel



#### For additional information please visit our website at: www.ixysic.com

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